

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.67814	100.0	9.8
			<b>Subtotal</b>	<b>0.67814</b>	<b>100</b>	<b>9.8</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.15777	100.0	2.28
	Pure metal	Aluminium (Al)	7429-90-5	0.02774	100.0	0.40092
			<b>Subtotal</b>	<b>0.18551</b>	<b>200</b>	<b>2.68092</b>
Post-plating	Pure Metal	Tin (Sn)	7440-31-5	1.72995	100.0	25
			<b>Subtotal</b>	<b>1.72995</b>	<b>100</b>	<b>25</b>
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.02325	0.04	0.336
	Copper alloy	Iron (Fe)	7439-89-6	0.05813	0.1	0.84
	Copper alloy	Copper (Cu)	7440-50-8	58.04481	99.86	838.824
			<b>Subtotal</b>	<b>58.12619</b>	<b>100</b>	<b>840</b>
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	3.38637	8.7	48.9375
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	6.22781	16.0	90
	Filler	Silica fused	60676-86-0	29.19284	75.0	421.875
	Carbon Black	Carbon black	1333-86-4	0.11677	0.3	1.6875
			<b>Subtotal</b>	<b>38.92379</b>	<b>100</b>	<b>562.5</b>
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.02774	100.0	0.40092
			<b>Subtotal</b>	<b>0.02774</b>	<b>100</b>	<b>0.40092</b>
Die Attach	Lead alloy	Tin (Sn)	7440-31-5	0.01643	5.0	0.2375
	Lead alloy	Silver (Ag)	7440-22-4	0.00822	2.5	0.11875
	Lead alloy	Lead (Pb)	7439-92-1	0.30404	92.5	4.39375
			<b>Subtotal</b>	<b>0.32869</b>	<b>100</b>	<b>4.75</b>
			<b>Total</b>	<b>100.00001</b>	<b>100</b>	<b>1445.13184</b>

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